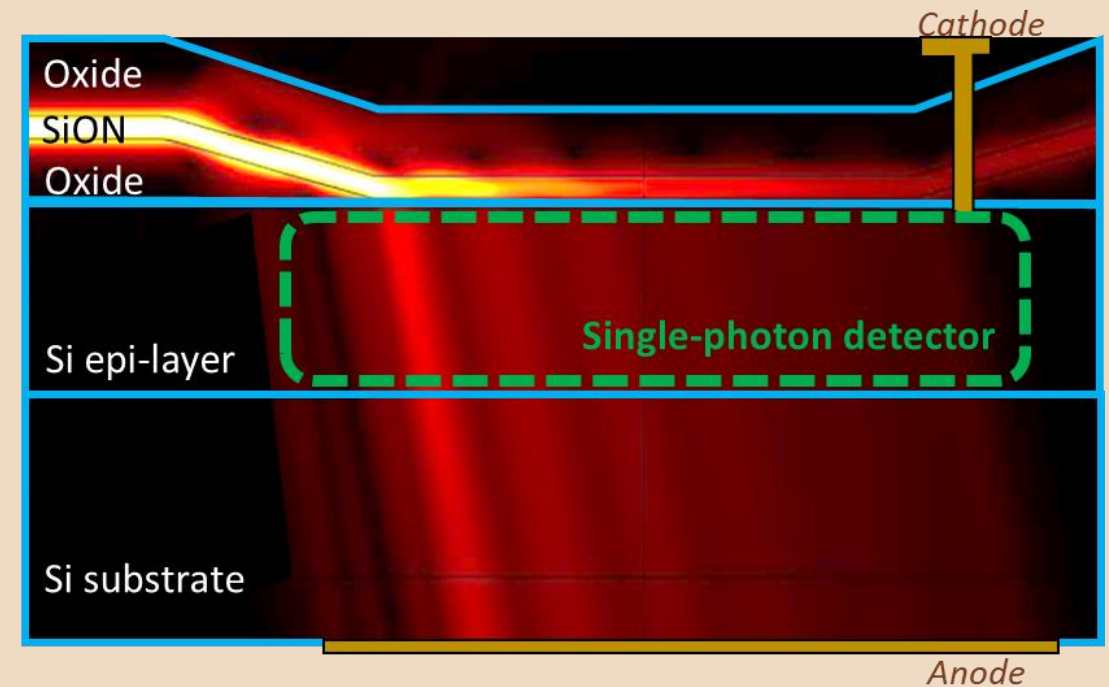




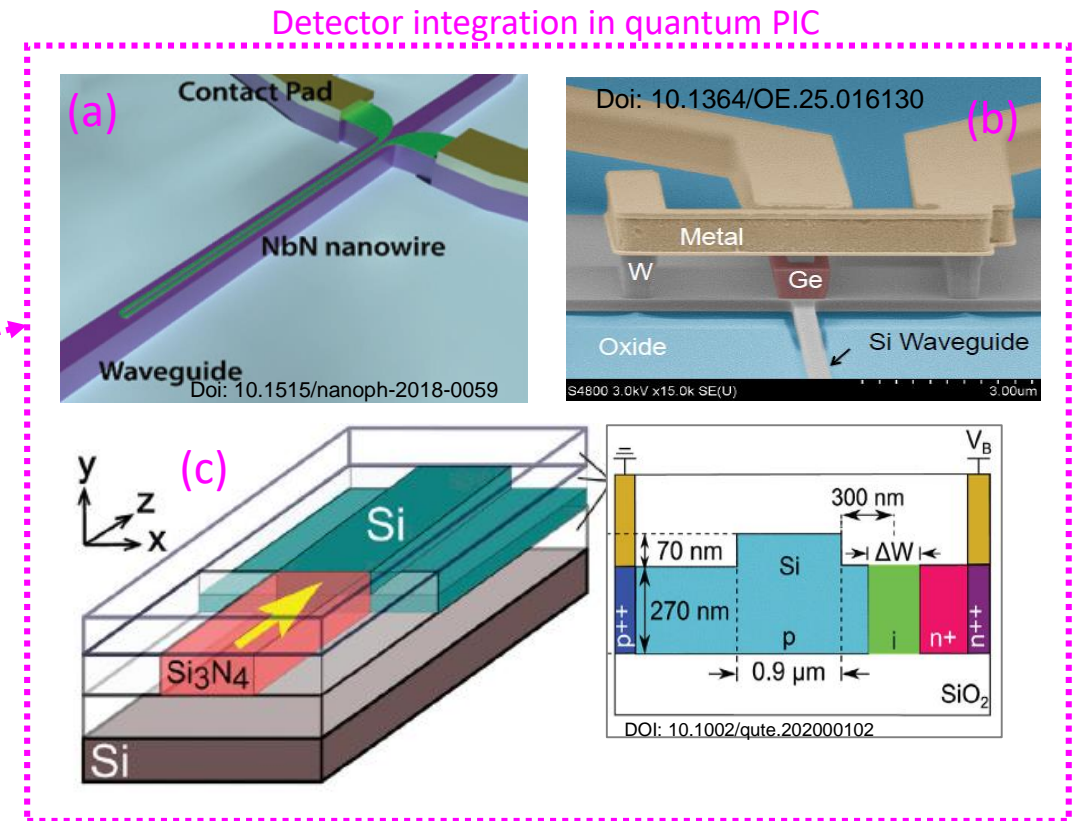
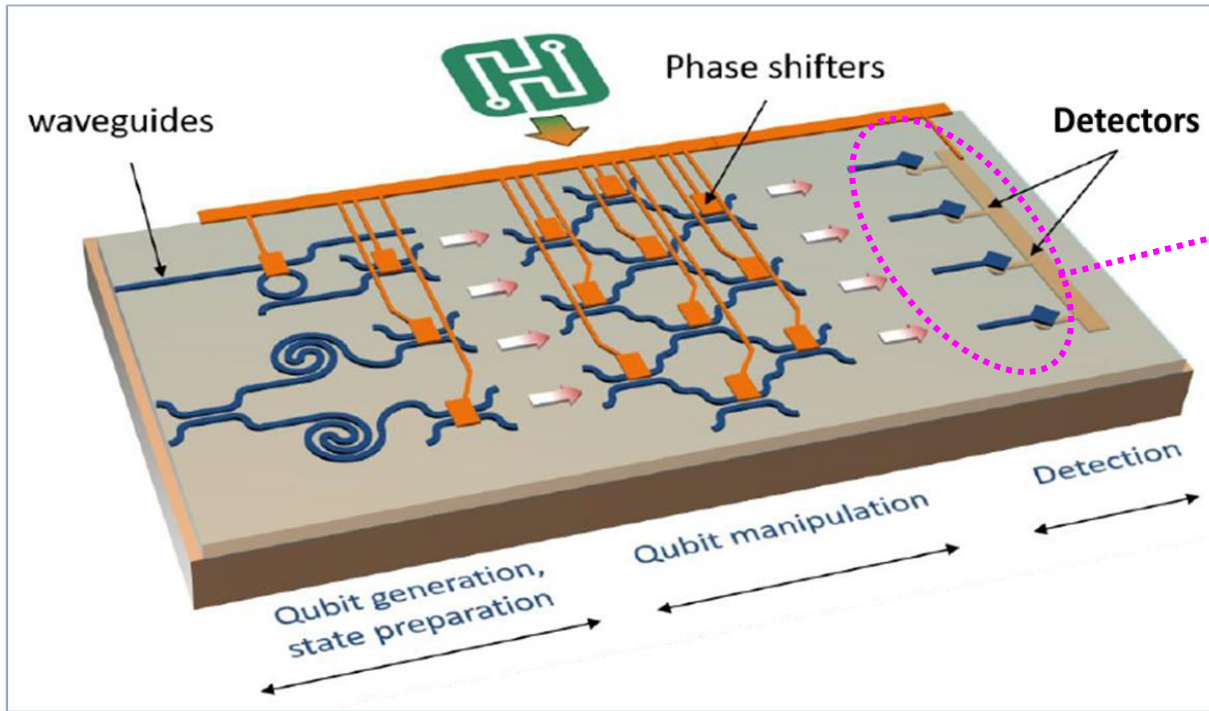
Monolithic Integration of SiON photonic-circuit and single-ph. detectors

**F. Acerbi, M. Bernard, G. Paternoster,
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Introduction



- **Important topic** in quantum photonics → **integration of photon source, manipulation and detection in the PICs.**
- Possible approach: - Si-based photonics (SWIR, e.g. 1550 nm) integrated with SNSPD, or with Ge-on-Si detectors;
- SiN (or SiON) photonics (NIR, e.g. 850nm) integrated with Si detectors.
- **FBK approach:** quantum PIC with SiN(SiON) waveguide monolithically integrated with Si-SPAD (**CMOS compatible**)

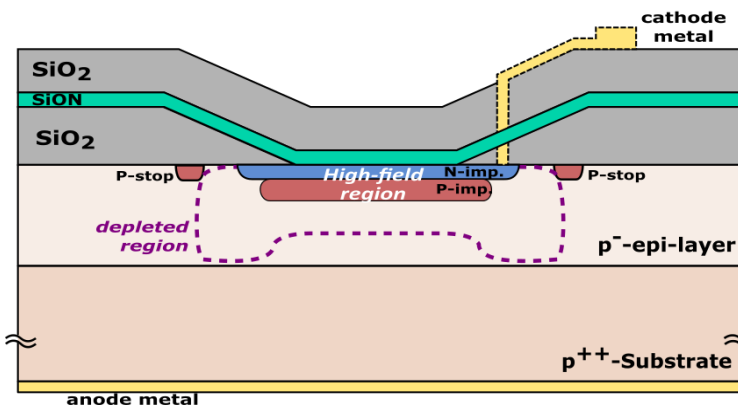
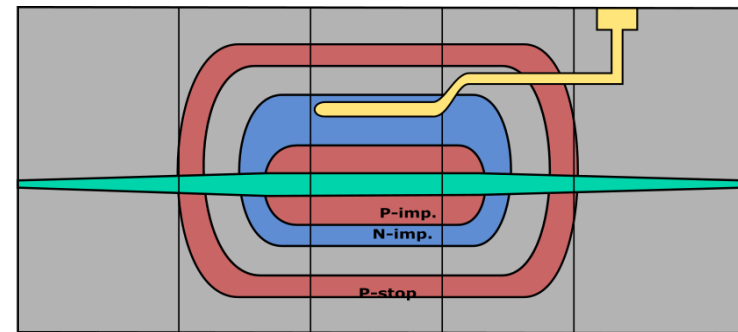
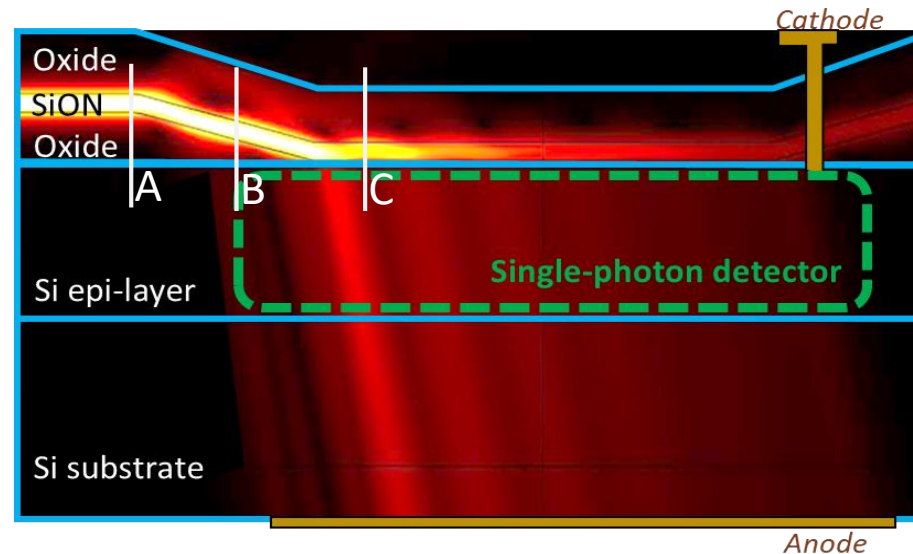
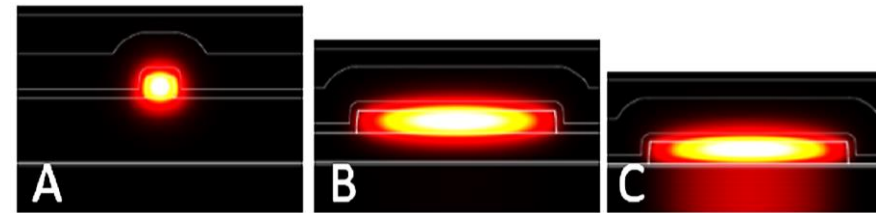
FBK photonic/electronic top-down coupling approach

➤ New efficient top-down evanescent coupling approach

➤ based on shaping of WG and cladding thickness.

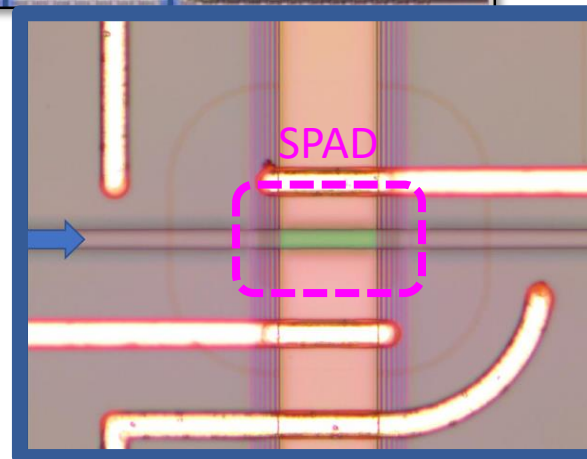
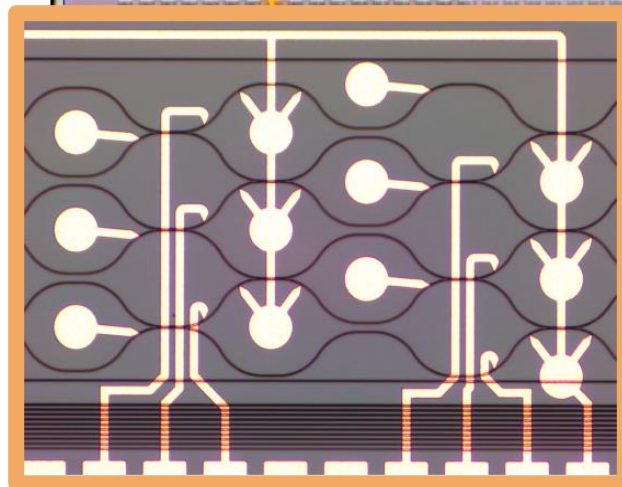
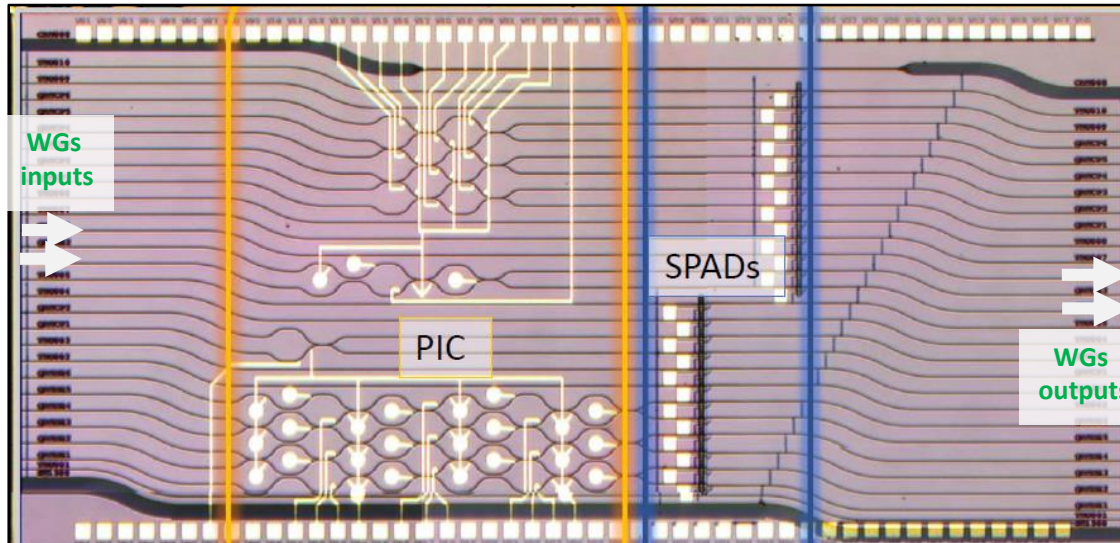
➤ Advantages:

1. materials all CMOS compatible (already used in CMOS);
2. not require alignments, butt coupling, ...etc...;
3. it operates at room temperature;
4. SPAD design does not have particular constraints.





Test chip: PIC+SPADs → *photon manipulation and detection*



- First implementation: *test chip developed within previous projects.*
- Several waveguides:
 - Inputs and outputs on opposite facets,
 - Each WG coupled to 1 SPAD
- Manipulation:
 - MZI, based on heaters
- Detection:
 - Si SPADs
 - FBK "RGB" Technology (n-on-p junction type)



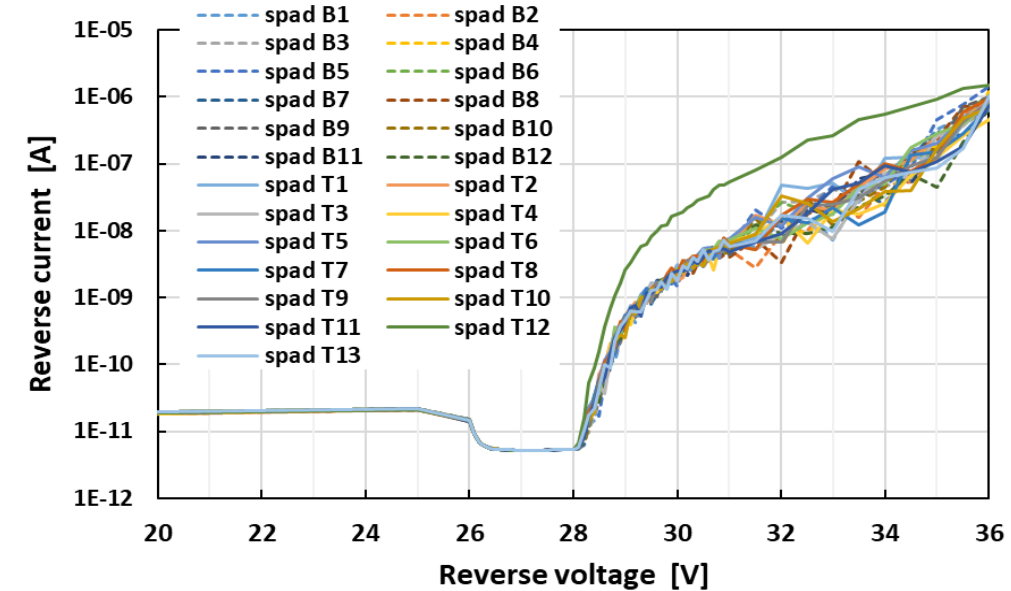
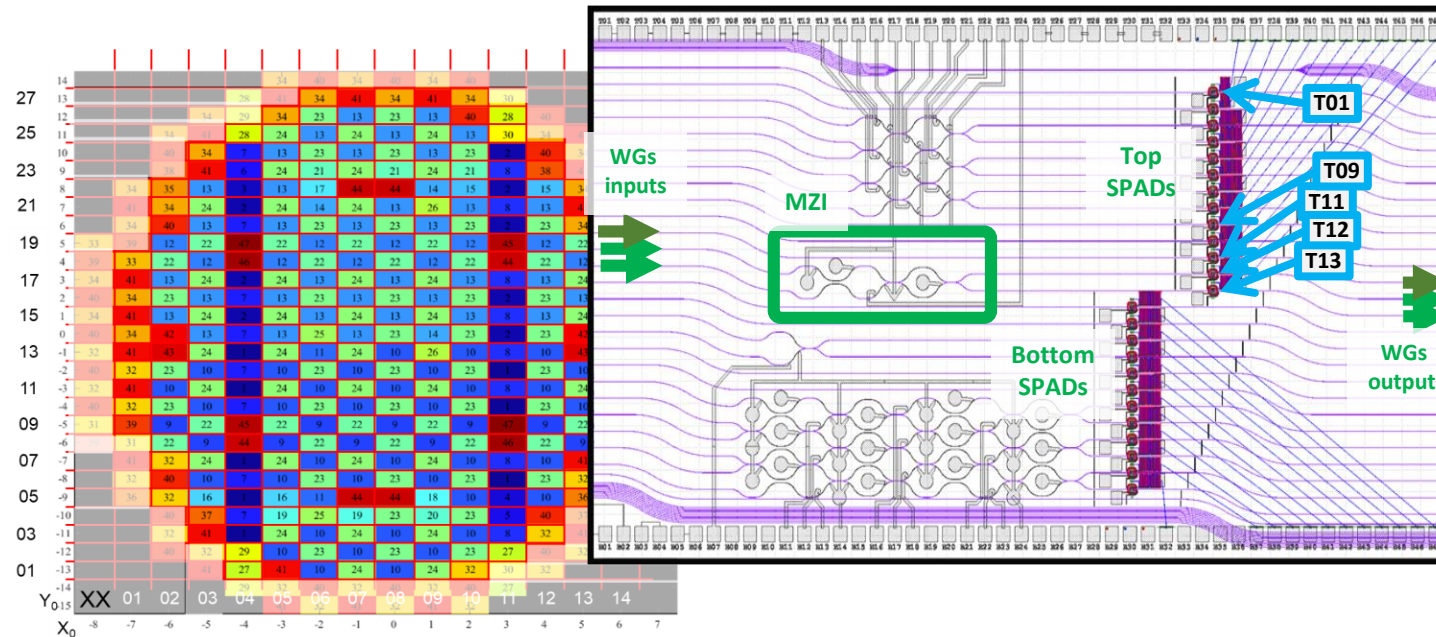
Grant agreement # 899368



Horizon 2020
European Union funding
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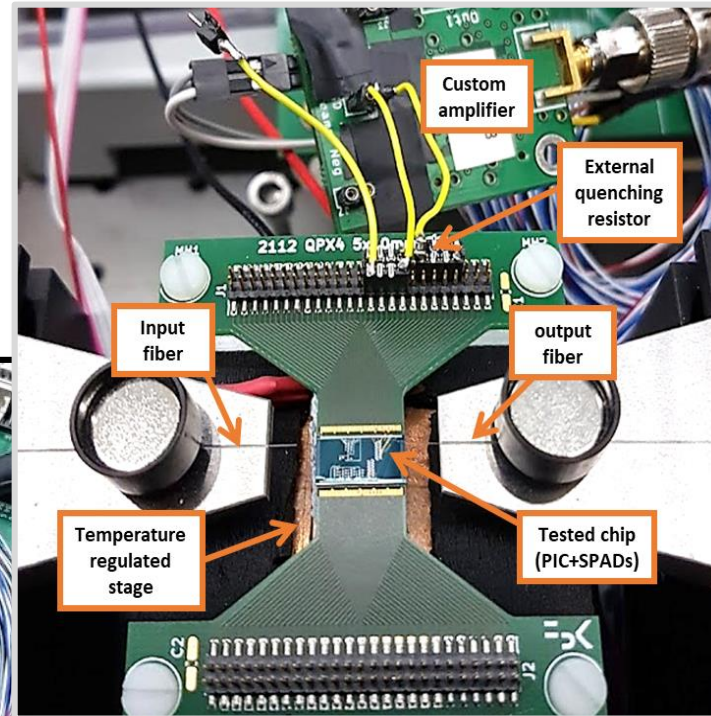
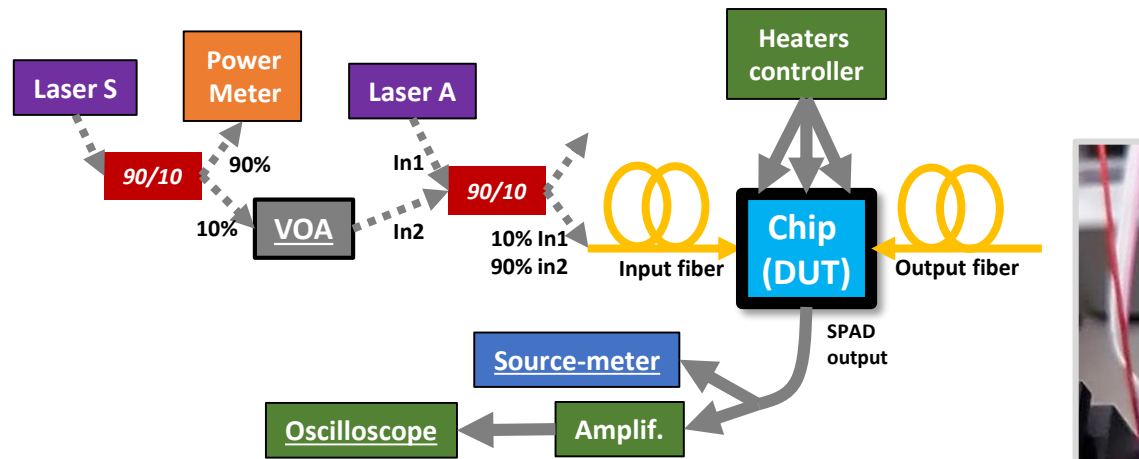
Electrical characterization



➤ ***Wafer level electrical testing → measurements of fw and reverse IV curves of diodes and SPADs***

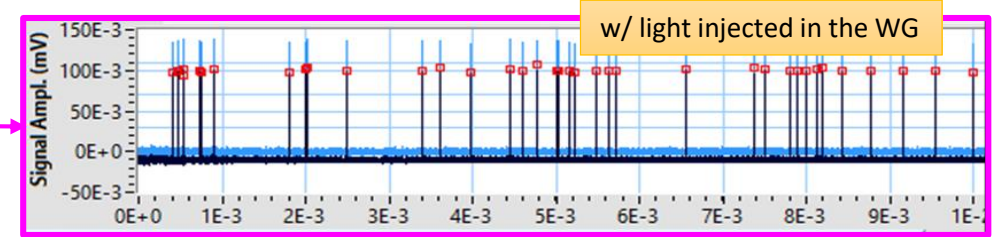
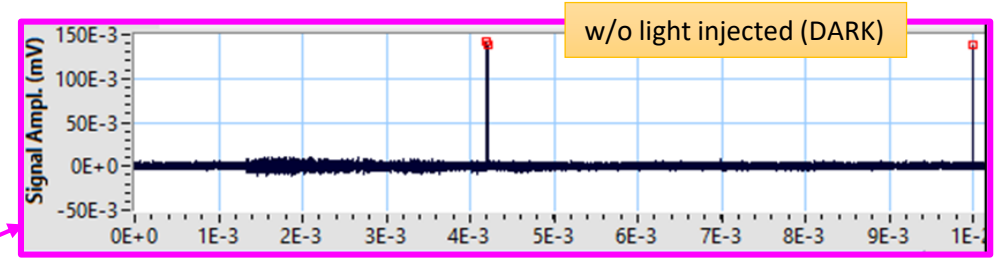
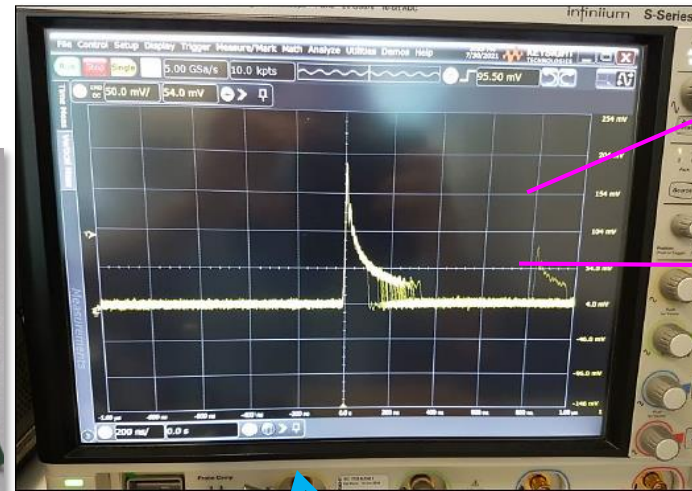
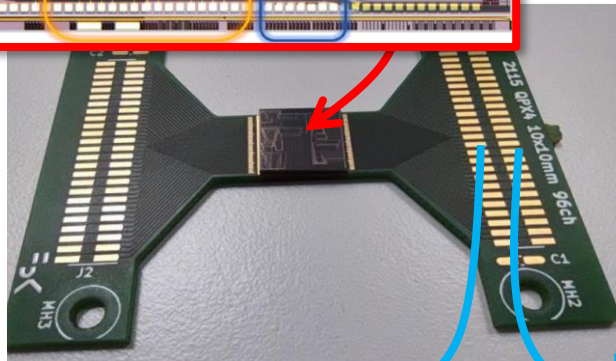
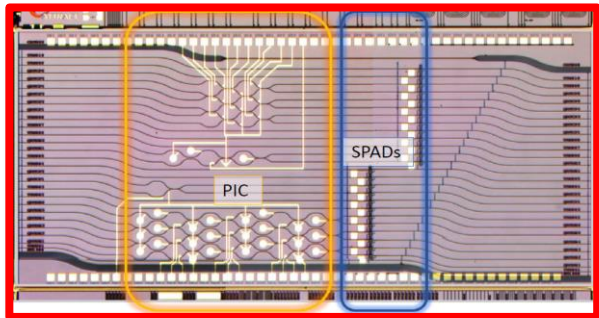
- Several chip tested
- Good uniformity in breakdown voltage in the SPADs (~28V)
- *Relatively low yield because of process-related issue → to be solved in future production*

Photonic/optoelectronic characterization



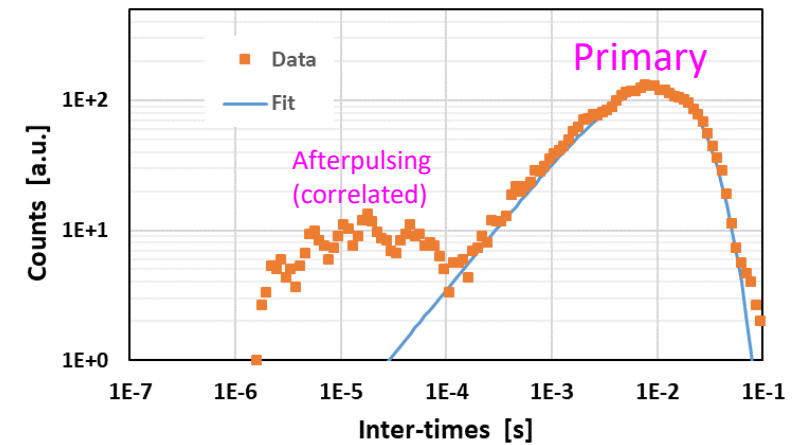
- Source laser (850 nm)
- Alignment laser
- Multiple variable optical attenuators:
 - Pre-calibration: with high light intensity
 - Use: to single-ph. Level
- TEC cooling
- SPADs:
 - External quench. resistors
 - Custom sig. amplifier

Pulse-counting performance

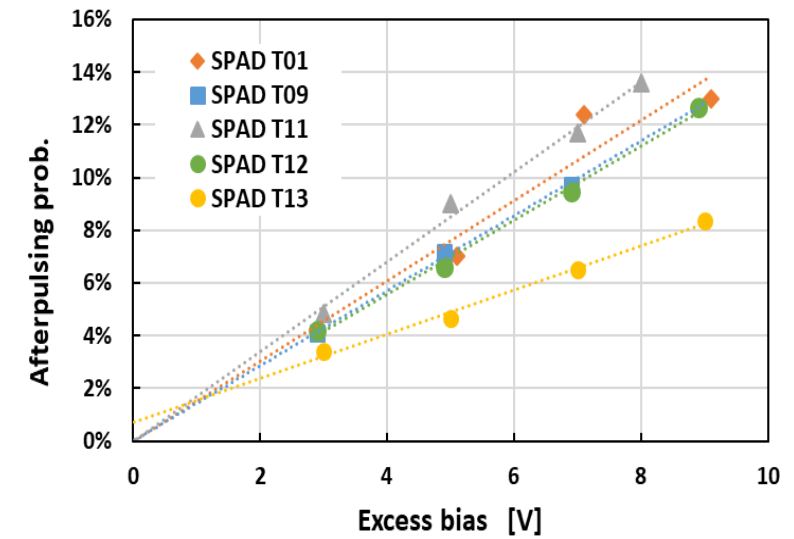
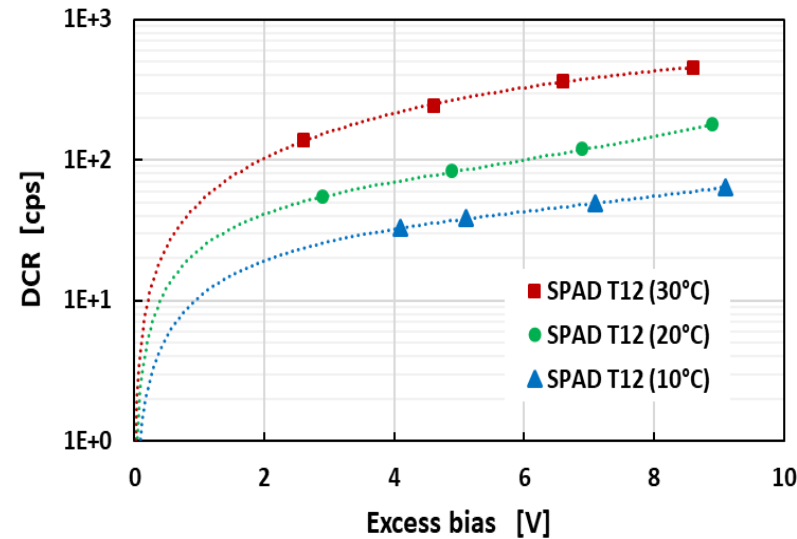
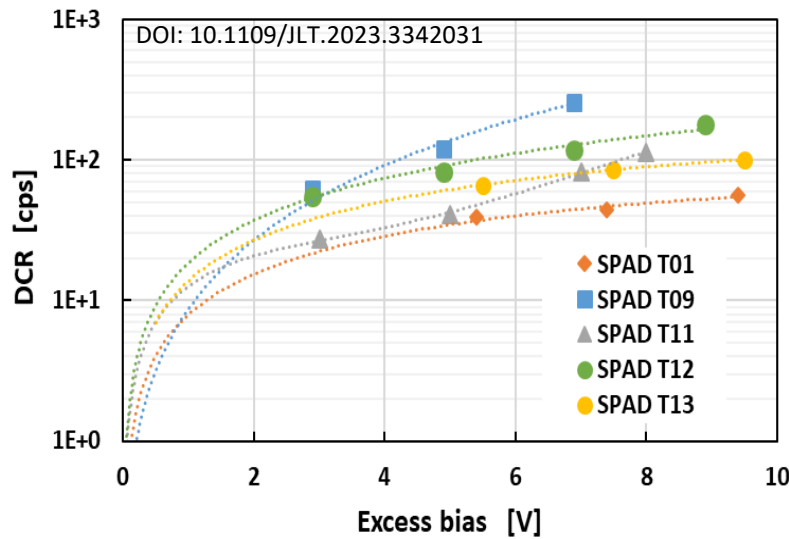


Amp

- SPAD pulse rate: proportional to the injected light intensity
- Inter-times between pulses → exponential statistics
→ extraction of primary and correlated events



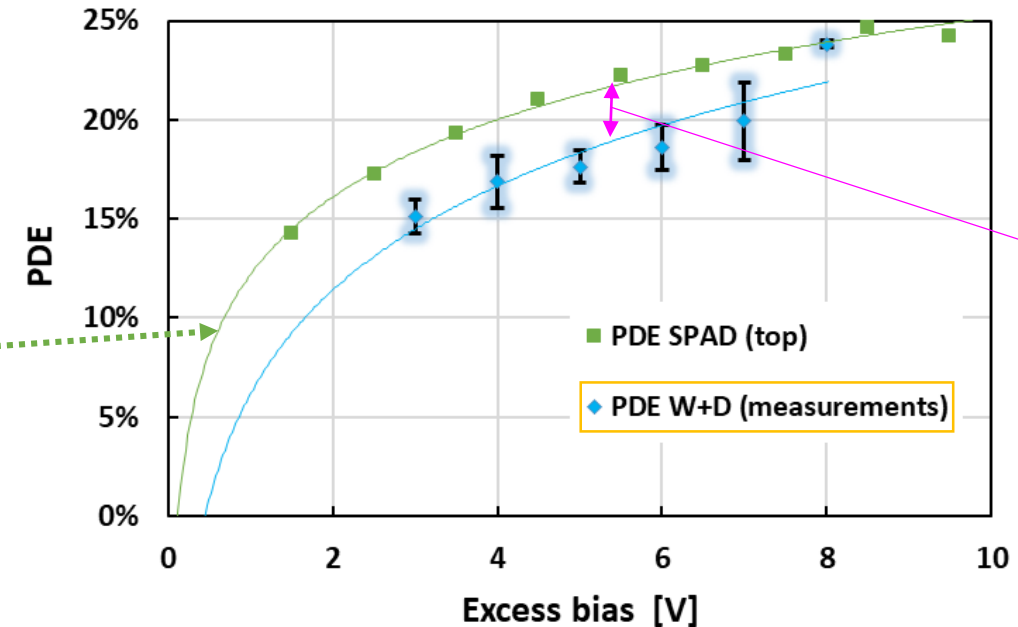
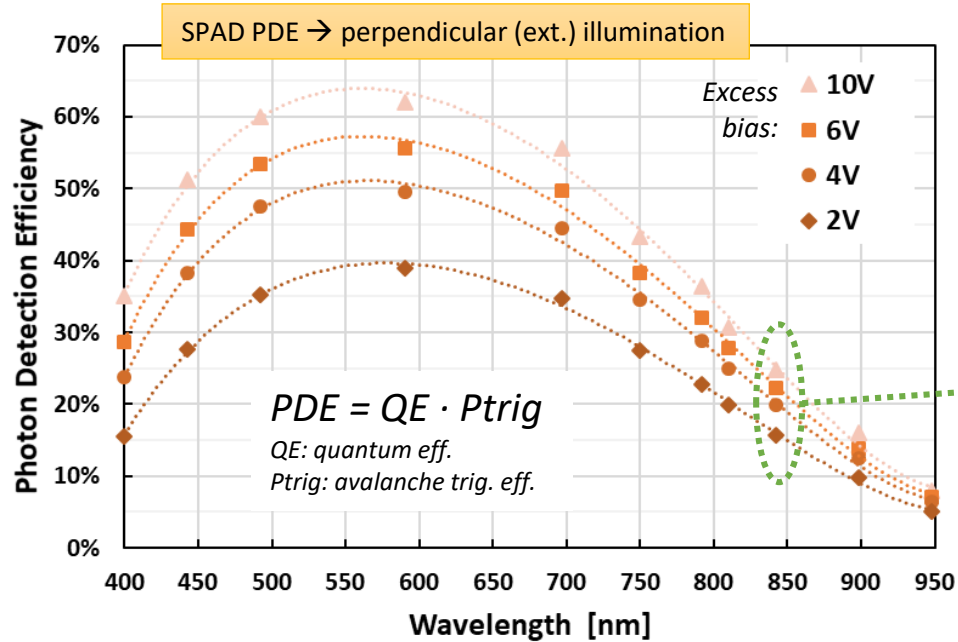
Pulse-counting performance



Excess bias: bias above the breakdown voltage

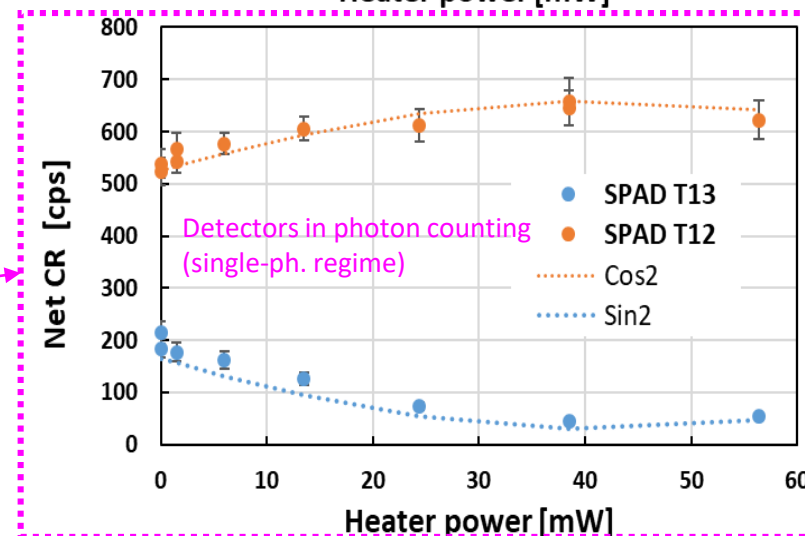
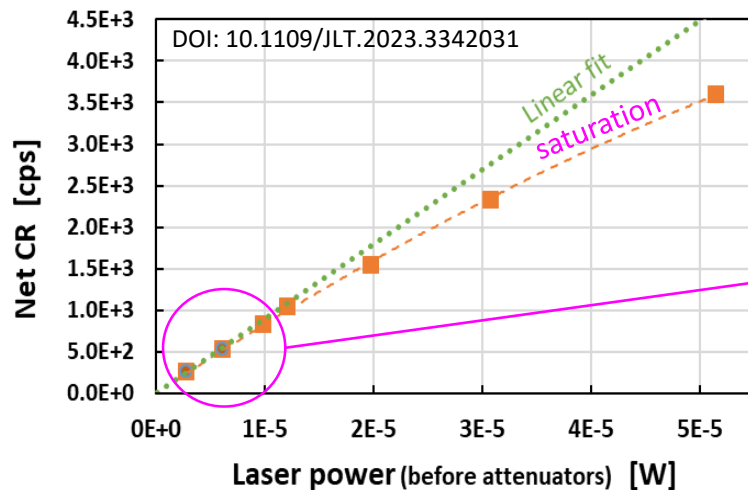
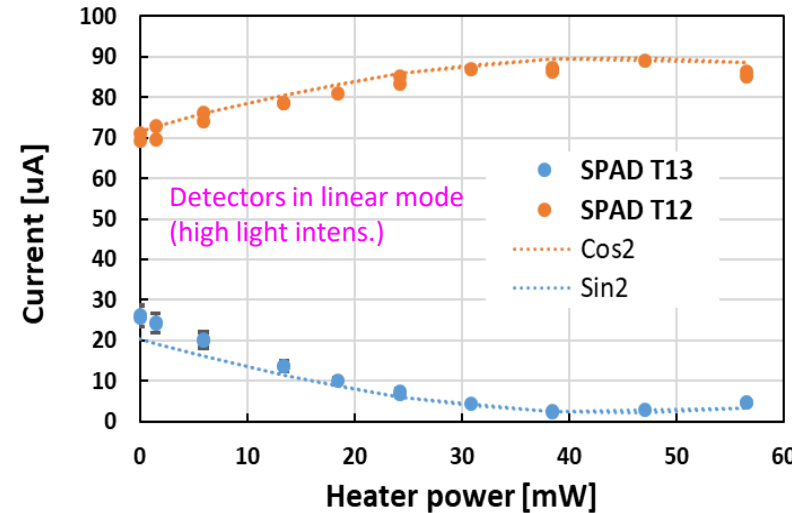
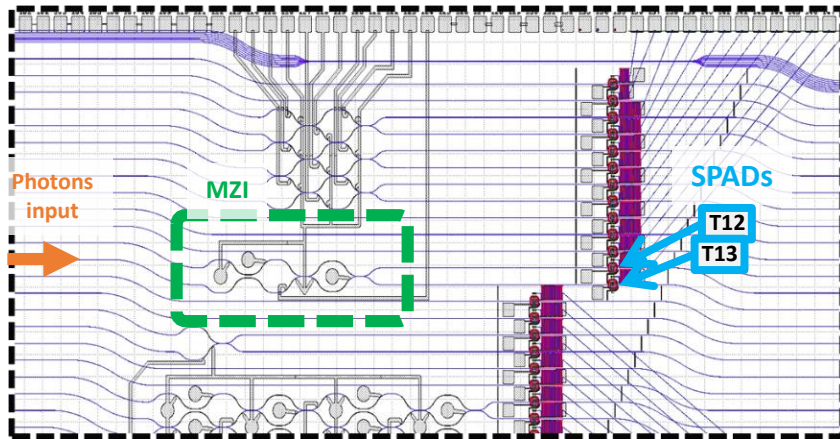
- Dark count rate (primary noise)
 - ~100 counts per second (cps) @ 20°C
 - in line with state-of-the-art Si-SPAD (commercial product)
- Temperature dependence: DCR halved about every 10°C
- Afterpulsing relatively high → *because of the external quenching (not optimized)(not the operative conditions)*

Detection efficiency and light-coupling efficiency



- Si-SPAD measurement with external light:
 - peaked in the green wavelength region; PDE= ~20% ÷ 25 % at 850nm
- laser light injected into WG + detection by SPAD:
 - Detection efficiency= ~17% ÷ 20 % at 850nm → WG-to-SPAD coupling efficiency= ~ 76% ÷ 85%

Light modulation with MZI



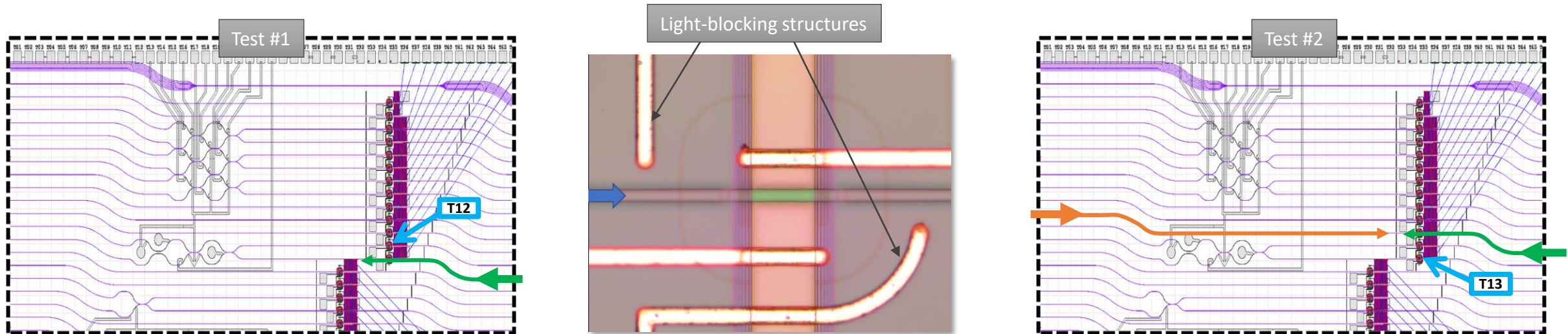
➤ Direct test of photon manipulation and detection

- Single photons injected.
- MZI (driven by heaters)
- 2 SPAD detectors

Procedure:

1. Selection of non-saturated power range
2. Heater power modulation
3. Count rate measurements (in the 2 SPADs)
4. Good agreement: photon counting behavior vs linear-mode behavior

Stray-light estimation



- Test #1: light from the right side WG associated to SPAD T13, monitoring SPAD T12.
 - we estimated a detection efficiency of about **0.04%**.
- Test #2: light from left or right side of WG associated to SPAD T11, monitoring SPAD T13
 - detection efficiency around **0.03%** (first case) and **0.16%** (second case).



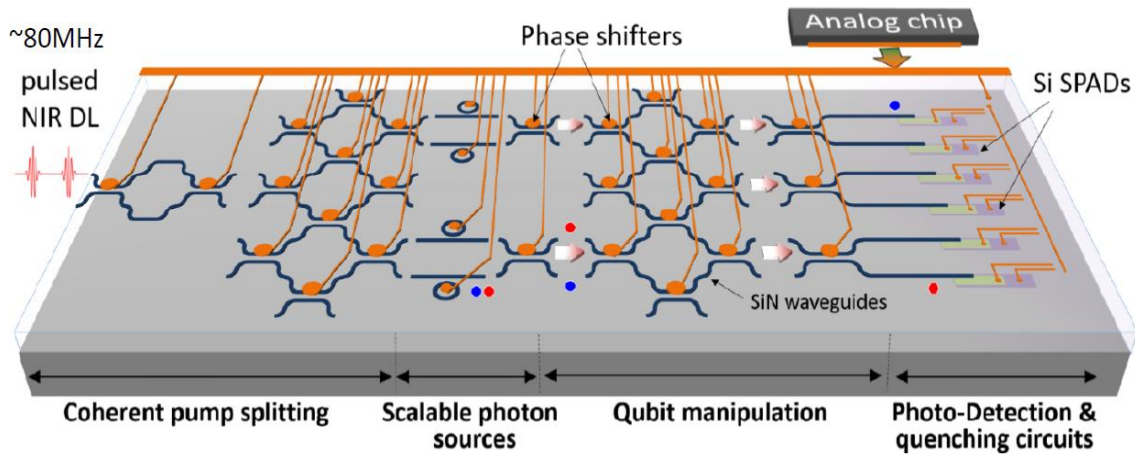
Conclusions

- New ***CMOS compatible top-down evanescent approach for monolithic electronic-photonic integration***
 - ✓ material all CMOS compatible,
 - ✓ it does not require alignments, butt coupling, or two waveguides made in different materials,
 - ✓ it can be operated at room temperature,
 - ✓ design of the SPADs does not have particular restrictions.
- Fabricated the first PIC based on SiON waveguide and with integrated silicon SPADs:
 - moderately low dark count rate
 - Good photon detection probability (improvable in future runs)
 - SPADs well appropriate for short gating pulses in a photonic quantum simulator.
 - system detection efficiency (i.e. PIC+SPAD), being between 17% and 20%
 - Waveguide-to-detectors coupling efficiency ~ 80%.
- Direct test of photon manipulation and detection:
 - Modulation of photons propagation between two adjacent waveguides and detection.
- Promising technology for future developments at FBK.
- Future runs: improvement of detection efficient (light trapping)



Acknowledgements

Electronic photonic integrated quantum simulator



Quantum Science and Technology in Trento



Q-PIXPAD

Quantum Photonic Circuits with monolithically integrated Silicon Single Photon Detectors



GA No 777222



Integrated photonic electronic platform for quantum technologies



Monolithic Integration of SiON photonic-circuit and single-ph. detectors

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